

## G1VL24C

SIDACs / Uni-directional (G1V Series)

190V, 280A

### Feature

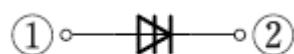
- Uni-directional
- Miniaturized compared to a K1V series
- For pulse generation, DC power with switching operation
- A reliable product with a track record, developed for many applications
- Pb free terminal
- RoHS:Yes

### OUTLINE

Package (House Name): 1F  
Package (JEDEC Code): DO-214AC



### Equivalent circuit



### Absolute Maximum Ratings (unless otherwise specified : TI=25°C)

Item	Symbol	Conditions	Ratings	Unit
Storage temperature	T <sub>stg</sub>		-40 to 150	°C
Junction temperature	T <sub>j</sub>		150	°C
Maximum off-state voltage	V <sub>DRM(A)</sub>		190	V
RMS on-state current	I <sub>T</sub>	TI=98°C, 50Hz sine wave, θ=180°	1	A
Pulse on-state current	I <sub>TRM</sub>	Ta=25°C, pulse width 10μs, 5Hz sine wave	280	A
Critical rate of rise of on-state current	di <sub>T</sub> /dt		150	A/μs

\* : See the original Specifications

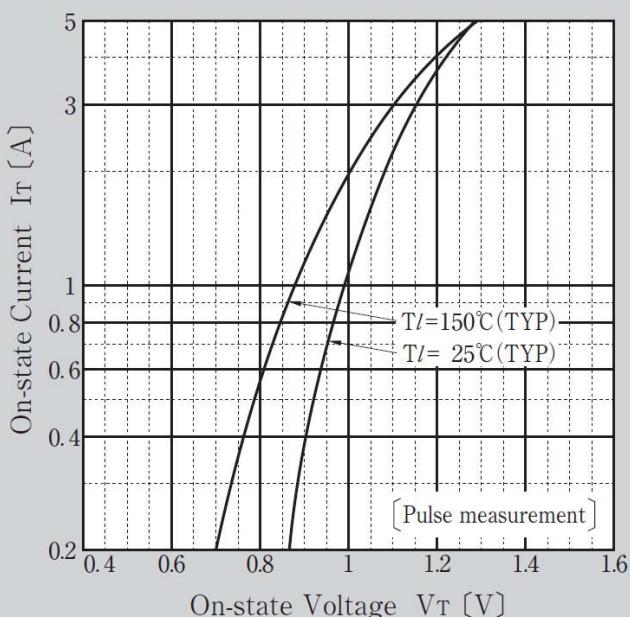
**Electrical Characteristics** (unless otherwise specified : Tj=25°C)

Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	
Breakover voltage	V <sub>BO(A)</sub>	Pulse measurement, dv/dt=4V/ms	230		250	V
Off-state current	I <sub>DRM(A)</sub>	VD=190V			10	µA
Breakover current	I <sub>BO(A)</sub>	VBO-0.5V			0.5	mA
Holding current	I <sub>H(A)</sub>				60	mA
Holding current	I <sub>H(K)</sub>				60	mA
On-state voltage	V <sub>T(A)</sub>	IT=1A			1.5	V
On-state voltage	V <sub>T(K)</sub>	IT=1A			1.5	V
Switching resistance	R <sub>S(A)</sub>		0.1			kΩ
Thermal resistance	R <sub>th(j-l)</sub>	Junction to lead			23	°C/W

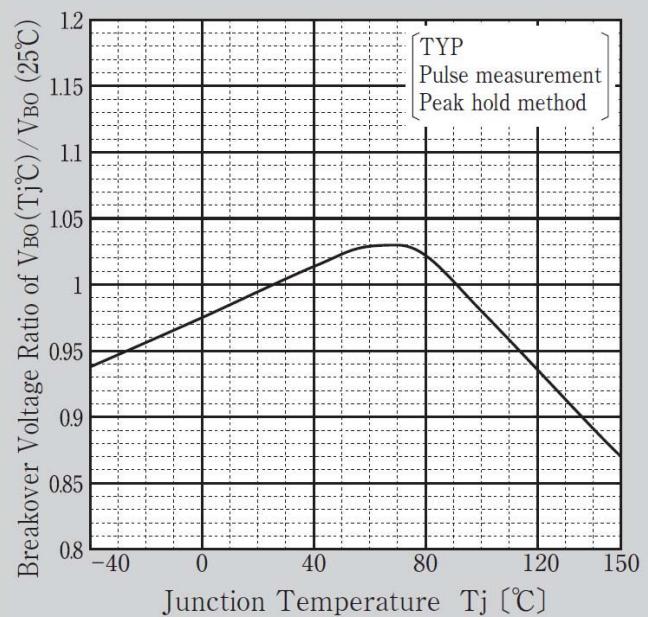
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## CHARACTERISTIC DIAGRAMS

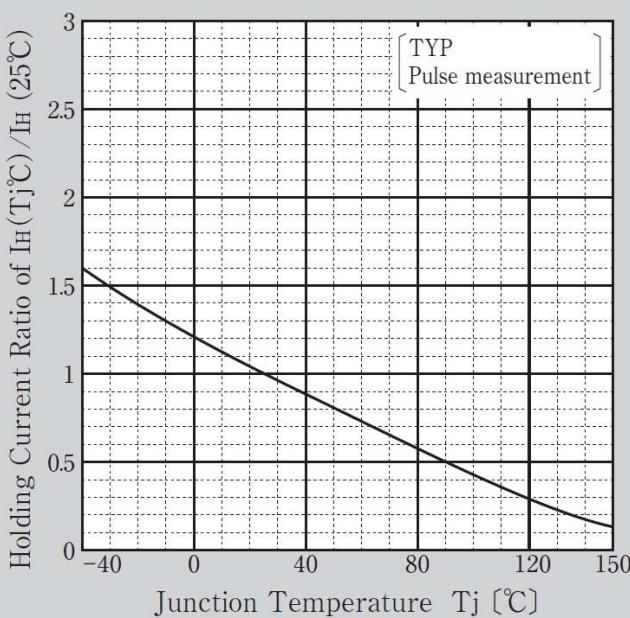
On-state Voltage vs On-state Current



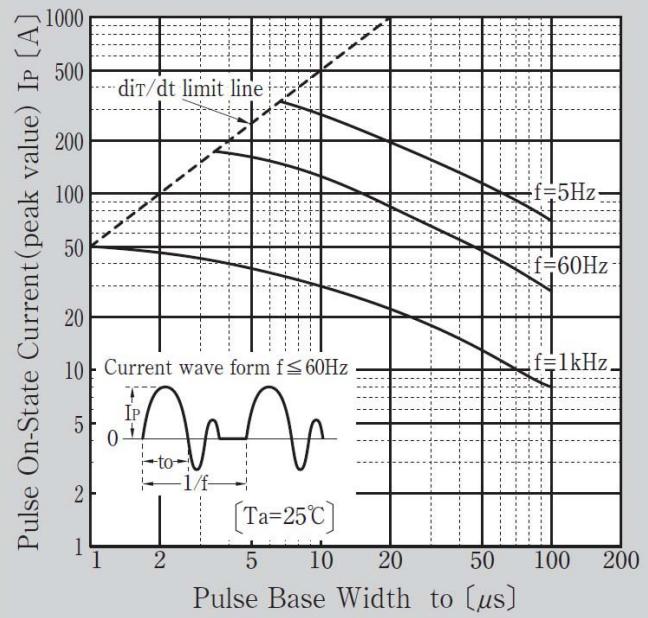
Breakover Voltage vs Junction Temperature

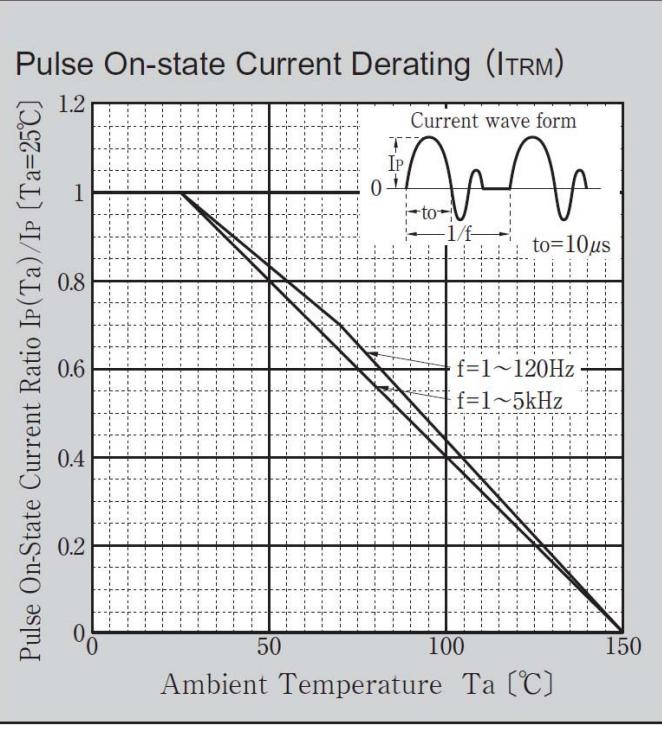


Holding Current vs Junction Temperature



Pulse On-state Current Rating ( $I_{TRM}$ )





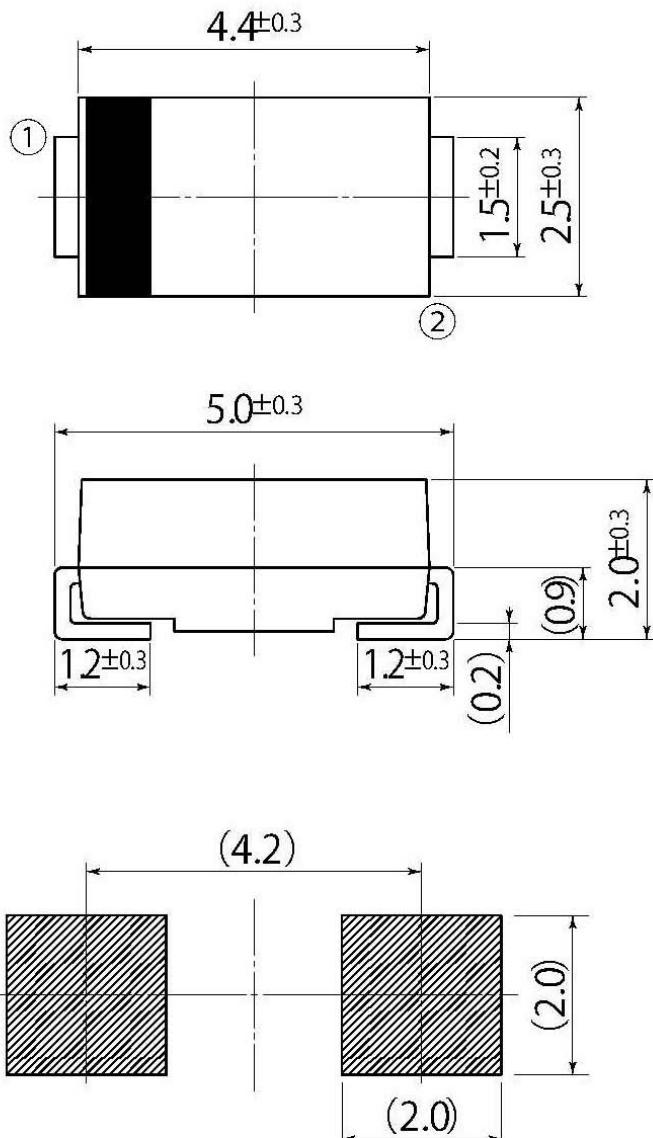
## Outline Dimensions

unit:mm

scale: 10/1

B3

JEDEC Code	DO-214AC
JEITA Code	-
House Name	1F, CF



Referential Soldering Pad

- Optimize soldering pad to the board design and soldering condition.